

What is claimed is:

1. A semiconductor package comprising:  
a substrate including a redundant bond finger, an added bond finger connected to a  
5 redundant solder ball pad;  
a semiconductor chip having an added bond pad attached to the substrate;  
a normal wire bonding unit coupled between the added bond pad and the redundant  
bond finger; and  
an added wire bonding unit coupled between the redundant bond finger and the added  
10 bond finger.

2. The semiconductor package of claim 1, further comprising:  
an encapsulant for encapsulating the semiconductor chip, the normal and added wire  
15 bonding units.

3. The semiconductor package of claim 2, further comprising:  
a solder ball connected to the redundant solder ball pad.

4. The semiconductor package of claim 1, wherein the substrate is a single-layer  
20 substrate on which a printed circuit pattern is formed.

5. The semiconductor package of claim 1, wherein the substrate is a double-layer  
substrate or a multi-layer substrate.

6. The semiconductor package of claim 1, wherein a solder mask is not formed  
25 on the added bond finger.

7. The semiconductor package of claim 1, wherein the added wire bonding unit  
is formed over the substrate.

8. The semiconductor package of claim 1, wherein the added wire bonding unit  
30 is formed on an outer region of the substrate on which the semiconductor chip is mounted.

9. The semiconductor package of claim 1, wherein the added wire bonding unit is one unit or a plurality of units.

10. The semiconductor package of claim 1, wherein the semiconductor chip is attached to the substrate using an adhesive.

11. The semiconductor package of claim 1, wherein the added bond finger is made by further extending the printed circuit pattern on the substrate.

12. The semiconductor package of claim 1, wherein the added bond finger has the same pad shape as that of the redundant bond finger.

13. A semiconductor package comprising:  
a substrate including a first printed circuit pattern connected to a redundant bond finger and a second printed circuit pattern connected to a redundant solder ball pad;  
a semiconductor chip attached to the substrate; and  
an added wire bonding unit coupled between the first printed circuit pattern to the second printed circuit pattern.

14. The semiconductor package of claim 13, further comprising:  
an encapsulant for encapsulating the semiconductor chip and the added wire bonding unit.

15. The semiconductor package of claim 14, further comprising:  
a solder ball connected to the redundant solder ball pad.

16. The semiconductor package of claim 13, wherein the first and second printed circuit patterns each have a width that enables wire bonding to be performed thereon.

17. A method for manufacturing a semiconductor package, the method comprising:

forming an added bond finger coupled to a redundant solder ball pad, and a redundant bond finger on a substrate;

attaching a semiconductor chip having an added bond pad to the substrate ;

forming a normal wire bonding unit coupled between the added bond pad to the  
5 redundant bond finger; and

forming an added wire bonding unit coupled between the redundant bond finger to the added bond finger.

18. The method of claim 17, further comprising:

10 encapsulating the semiconductor chip, the normal wire bonding unit, and the added wire bonding unit.

19. The method of claim 18, further comprising:

attaching a solder ball to a solder ball pad including the redundant solder ball pad.

20. The method of claim 17, wherein the substrate is a single-layer substrate, a double-layer substrate, or a multi-layer substrate.

21. The method of claim 17, wherein the added wire bonding is performed on an  
20 outer region of the substrate on which the semiconductor chip is attached.

22. The method of claim 17, wherein a single added wire bonding unit or a plurality of added wire bonding units are formed during performing the added wire bonding.

23. A method for manufacturing a semiconductor package, the method comprising:

preparing a substrate including a first printed circuit pattern connected to a redundant bond finger and a second printed circuit pattern connected to a redundant solder ball pad;

attaching a semiconductor chip to the substrate; and

30 forming an added wire bonding unit coupled between the first printed circuit pattern and the second printed circuit pattern.

24. The method of claim 23, further comprising:  
encapsulating the semiconductor chip and the added wire bonding unit.

25. The method of claim 24, further comprising:  
attaching a solder ball to a solder ball pad including the redundant solder ball pad.

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